# XN01212 (XN1212)

### Silicon NPN epitaxial planar type

For switching/digital circuits

#### Features

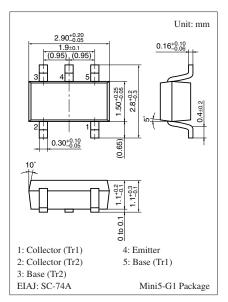
- Two elements incorporated into one package (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

#### Basic Part Number

• UNR2212 (UN2212) × 2

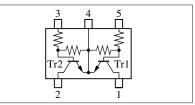
| Symbol           | Rating   | Unit   |  |  |  |  |  |
|------------------|--|--|--|--|--|--|--|
| V <sub>CBO</sub> | 50   | V  |  |  |  |  |  |
| V <sub>CEO</sub> | 50   | V  |  |  |  |  |  |
| I <sub>C</sub>   | 100  | mA   |  |  |  |  |  |
| P <sub>T</sub>   | 300  | mW   |  |  |  |  |  |
| Tj               | 150  | °C   |  |  |  |  |  |
| T <sub>stg</sub> | -55 to +150  | °C   |  |  |  |  |  |
|                  | Symbol<br>V <sub>CBO</sub><br>V <sub>CEO</sub><br>I <sub>C</sub><br>P <sub>T</sub><br>T <sub>j</sub> | Symbol Rating   V <sub>CBO</sub> 50   V <sub>CEO</sub> 50   I <sub>C</sub> 100   P <sub>T</sub> 300   T <sub>j</sub> 150 |  |  |  |  |  |





#### Marking Symbol: 9K

#### Internal Connection



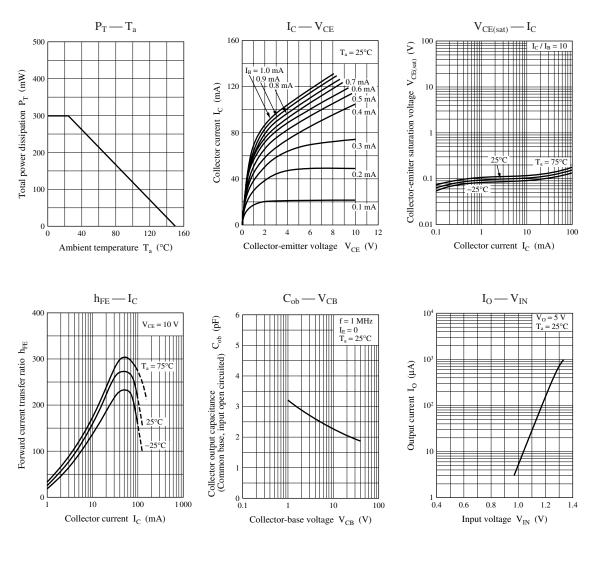
| Parameter                                    | Symbol                          | Conditions  | Min  | Тур  | Max  | Unit |
|--|---------------------------------|---|------|------|------|------|
| Collector-base voltage (Emitter open)        | V <sub>CBO</sub>                | $I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$   | 50   |      |      | V    |
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>                | $I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$   | 50   |      |      | V    |
| Collector-base cutoff current (Emitter open) | I <sub>CBO</sub>                | $V_{CB} = 50 \text{ V}, I_E = 0$  |      |      | 0.1  | μΑ   |
| Collector-emitter cutoff current (Base open) | I <sub>CEO</sub>                | $V_{CE} = 50 \text{ V}, I_B = 0$  |      |      | 0.5  | μΑ   |
| Emitter-base cutoff current (Collector open) | I <sub>EBO</sub>                | $V_{EB} = 6 V, I_C = 0$   |      |      | 0.2  | mA   |
| Forward current transfer ratio               | h <sub>FE</sub>                 | $V_{CE} = 10 \text{ V}, \text{ I}_{C} = 5 \text{ mA}$                                     | 60   |      |      |      |
| h <sub>FE</sub> Ratio *                      | h <sub>FE(Small</sub>           | $V_{CE} = 10 \text{ V}, \text{ I}_{C} = 5 \text{ mA}$                                     | 0.50 | 0.99 |      |      |
|  | /Large)                         |   |      |      |      |      |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub>            | $I_{C} = 10 \text{ mA}, I_{B} = 0.3 \text{ mA}$   |      |      | 0.25 | V    |
| Output voltage high-level                    | V <sub>OH</sub>                 | $V_{CC} = 5 \text{ V},  \text{V}_{B} = 0.5  \text{V},  \text{R}_{L} = 1  \text{k} \Omega$ | 4.9  |      |      | V    |
| Output voltage low-level                     | V <sub>OL</sub>                 | $V_{CC} = 5 \text{ V}, \text{ V}_{B} = 2.5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega$  |      |      | 0.2  | V    |
| Input resistance                             | R <sub>1</sub>                  |   | -30% | 22   | +30% | kΩ   |
| Resistance ratio                             | R <sub>1</sub> / R <sub>2</sub> |   | 0.8  | 1.0  | 1.2  | _    |
| Transition frequency                         | f <sub>T</sub>                  | $V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$                         |      | 150  |      | MHz  |

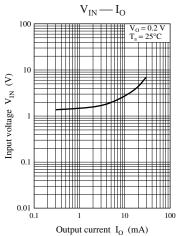
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Ratio between 2 elements

Note) The part number in the parenthesis shows conventional part number.

## Panasonic





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